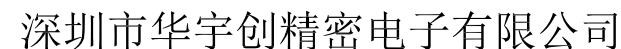
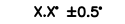


 PAD AREA
 KEEP OUT AREA
 GND PATTERN ONLY

NOTES :

- 1.Material:
 - 1.1 Insulator:High Temperature Thermoplastic,
(LCP,E130I),UL Black 94V-0.
 - 1.2 Contact: Phosphor Bronze(C5191-EH,T=0.15±0.03mm)
 - 1.3 Shell: SUS304-3/4H,T=0.15±0.03mm
- 2 Plating:
 - 2.1 Contact: Plated 50u"min Ni Overall
Plated 1u"min Au Selective Contact Area
Plated 80u"min Sn over Ni on solder area
 - 2.2 Shell: Plated 50u"min Ni Overall
- 3.Property:
 - 3.1 Current Rating :0.5A AC/DC
 - 3.2 Voltage Rating :250VRMS
 - 3.3 Dielectric Withstanding Voltage: AC 500V r.m.s.
 - 3.4 Insulation Resistance:1000MΩ minimum.
 - 3.5 Contact Resistance:100mΩ maximum
 - 3.6 Insertion Force:10N Max
 - 3.7 Separation Force: 2N Min
 - 3.8 Operating Temperature:-25°C~90°C
4. Part Must Comply Taisol HF WD-3-I-091 Specification.
5. Recommending A Metal More Than 0.15mm Thick. Please Confirm Solderability, IF Use A Metal Mass Less Than 0.15mm Thick



TOLERANCE:		DRAWN BY : 陈一鸣	DATE : 2014-02-23	PART NAME:	
X.X ±0.30 X.XX ±0.25 X.XXX ±0.15 X' ±2" X.X' ±0.5"				SD NO PUSH 短体板下DIP 沉板 1.75	
 UNIT: mm [inch]		CHECKED BY:	DATE :	PART NO.	HYC101-SD11-175
		马跃	2014-02-23	MOLD NO.	
		APPROVED BY:	DATE :	DRAW NO:	HYC-2509091623
SCALE:1:1	SIZE: A4	邱敏	2014-02-23	SHEET NO.	1 OF 1